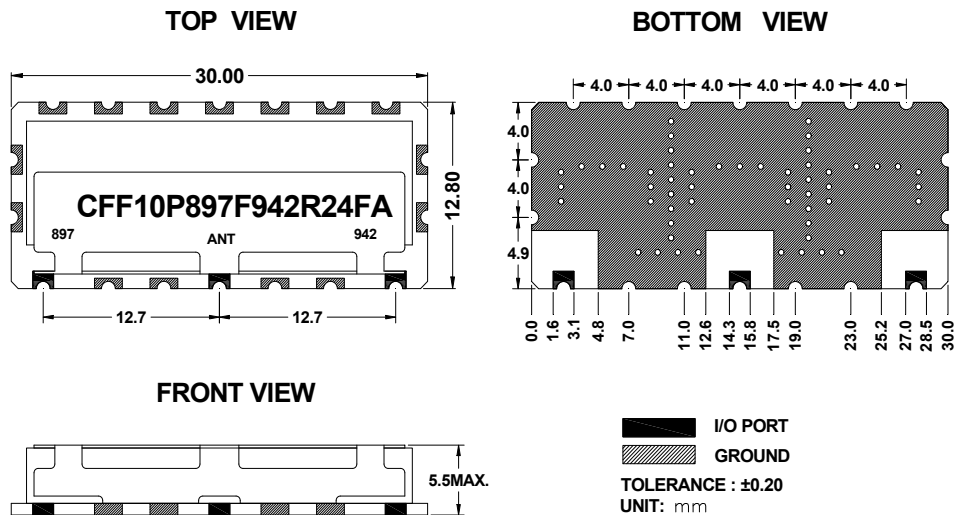


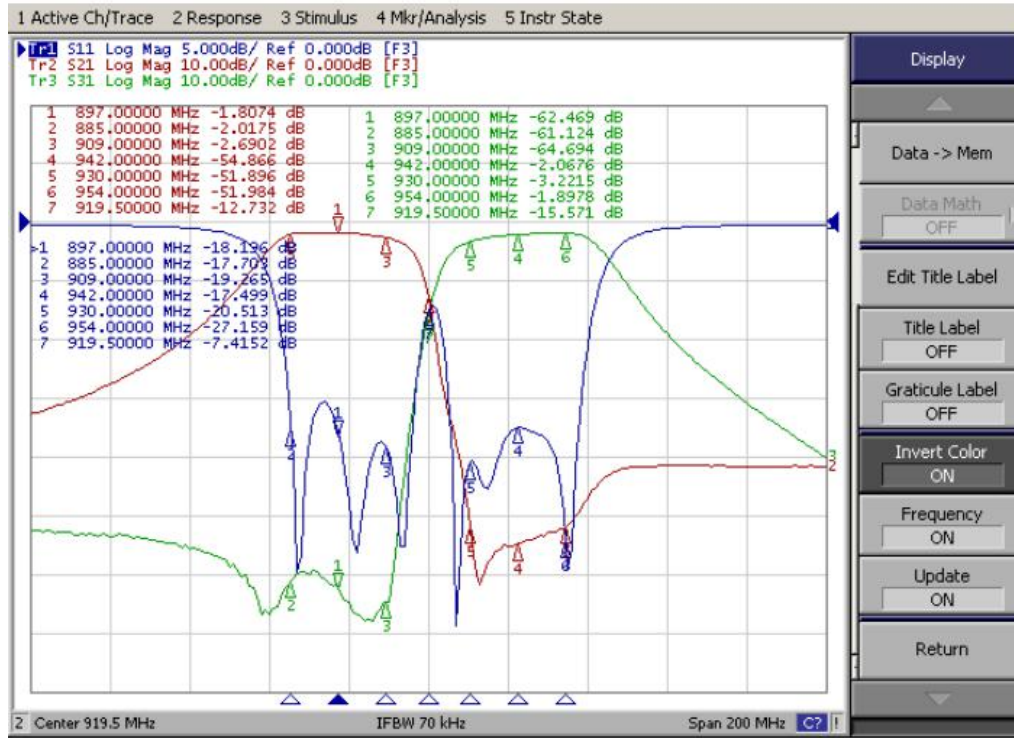
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	897.0	942.0	MHz
Bandwidth [BW]	fo ±12.0 [885.0~909.0]	fo ±12.0 [930.0~954.0]	MHz
Insertion Loss in BW	3.0	3.5	dB max
Ripple in BW	1.7	1.7	dB max
Return Loss in BW	13.0	13.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	45.0 dBmin. @ [930.0~954.0]	50.0dBmin.@[885.0~909.0]	MHz
	dBmin. @ [~]	dBmin. @[~]	MHz
	dBmin. @ [~]	dBmin. @[~]	MHz
	dBmin. @ [~]	dBmin. @[~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

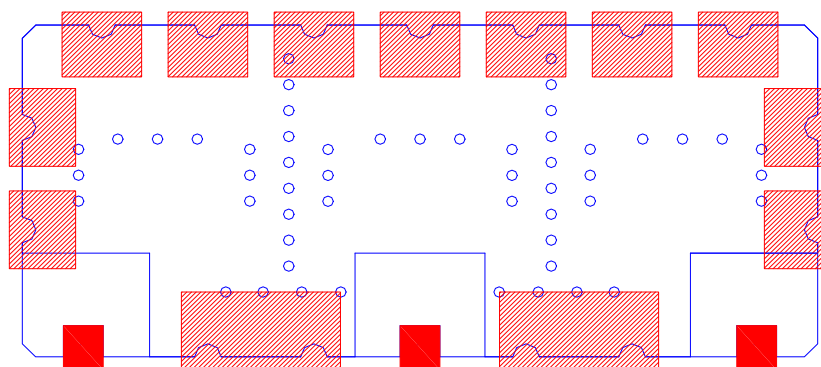
Mechanical Specification



Plot Data

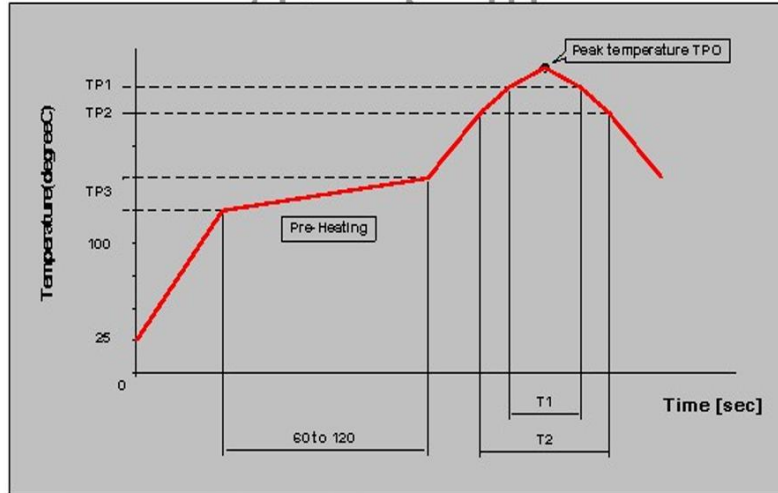


Recommended PC Board Pattern



I/O PORT SOLDERING POINT
GROUND SOLDERING POINT

 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180